



**FOR IMMEDIATE RELEASE**

**EV GROUP ADVANCES SOI LEADERSHIP AND PRESENCE IN CHINA  
WITH FIRST ORDER FROM SOI SUPPLIER SHENYANG SILICON TECHNOLOGY**

**SEMICON CHINA 2011, Shanghai, March 15, 2011** – [EV Group \(EVG\)](#), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced that new customer Shenyang Silicon Technology Co., Ltd. (SST) has placed an order for an [EVG850LT automated production bonding system](#) for silicon-on-insulator (SOI) wafers. The China-U.S. joint venture firm will utilize the EVG850LT, which was shipped in September 2010, in its state-of-the-art SOI production facility to expedite its efforts to ramp up high-volume manufacture of SOI wafers.

According to SST President Hai Fengtao, the company chose the EVG wafer bonder based on the success of the high-throughput, high-yield EVG850. “As we have already begun high-volume SOI wafer production, we were impressed with the EVG system’s performance and capabilities,” said Fengtao. “As EVG is the market leader for SOI bonding equipment, leveraging their systems in our facility will help SST to achieve a smooth technology transfer from R&D to high-volume production, while assuring our customers that they are purchasing wafers manufactured on the industry-standard SOI bonding system.”

Research and consulting firm Markets and Markets (Dallas, Texas) estimates that the global SOI market will grow at a CAGR of 15.3% from 2010 to 2015 to reach \$1.3 billion by 2015, driven by applications such as MEMS and microprocessors used in computers and video games. Investments in new manufacturing plants are also fuelling market growth, as well as R&D initiatives and strategic collaborations aimed at launching new technologies and growing the customer base.

EV Group Executive Technology Director Paul Lindner noted, “Working with SST is an important milestone for EVG, as technology activity in this region of the world continues to expand. Moreover, working with SST marks a further step in our efforts to develop solutions that address today’s challenges as well as to explore advancements that will address future needs.” This collaborative focus began about 15 years ago when EVG first worked with leading research institutes and inventors of SOI as well as all early SOI adopters. Since then, EVG has added all of the world’s SOI wafer producers to its roster of customers, attracting new business with its focus on continuous, customer-driven technology innovation and improvement.

For media interested in learning more about EVG’s technology solutions, please visit EV Group at booth #3101 at SEMICON China in Shanghai where the company will be exhibiting from March 15-17, 2011.

**About EV Group**

EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers’ fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for major ICs and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.



**EVG RECEIVES SOI WAFER BONDER ORDER FROM CHINA'S SHENYANG SILICON TECHNOLOGY.....PAGE 2 OF 2**

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; Seoul, Korea and Chung-Li, Taiwan. The company's unique Triple-i approach (invent - innovate - implement) is supported by a vertical integration, allowing EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. More information is available at [www.EVGroup.com](http://www.EVGroup.com).

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